TOSHIBA Field Effect Transistor Silicon N Channel MOS Type (π–MOSV)

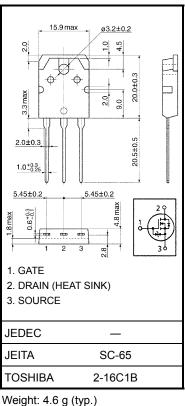
2SK2601

DC-DC Converter, Relay Drive and Motor Drive Applications

- Low drain-source ON resistance $: RDS (ON) = 0.75 \Omega (typ.)$
- High forward transfer admittance $: |Y_{fs}| = 7.0 \text{ S (typ.)}$
- Low leakage current $: I_{DSS} = 100 \ \mu A \ (max) \ (V_{DS} = 500 \ V)$
- Enhancement mode : $V_{th} = 2.0 \sim 4.0 \text{ V} (V_{DS} = 10 \text{ V}, \text{ I}_{D} = 1 \text{ mA})$

| Characteris | stics | Symbol | Rating | Unit | |
|---|------------------------|------------------|---------|------|--|
| Drain-source voltage | | V _{DSS} | 500 | V | |
| Drain-gate voltage (R | _{GS} = 20 kΩ) | V _{DGR} | 500 | V | |
| Gate-source voltage | | V _{GSS} | ±30 | V | |
| Drain current | DC (Note 1) | I _D | 10 | А | |
| | Pulse (Note 1) | I _{DP} | 40 | А | |
| Drain power dissipation | n (Tc = 25°C) | PD | 125 | W | |
| Single pulse avalanche energy (Note 2) | | E _{AS} | 270 | mJ | |
| Avalanche current | | I _{AR} | 10 | А | |
| Repetitive avalanche e | nergy (Note 3) | E _{AR} | 12.5 | mJ | |
| Channel temperature | | T _{ch} | 150 | °C | |
| Storage temperature ra | ange | T _{stg} | -55~150 | °C | |

Absolute Maximum Ratings (Ta = 25°C)



 Storage temperature range
 T stg
 -55~150
 °C

 Note:
 Using continuously under heavy loads (e.g. the application of high temperature/current/voltage and the significant change in temperature, etc.) may cause this product to decrease in the reliability significantly even if the operating conditions (i.e. operating temperature/current/voltage, etc.) are within the absolute maximum ratings. Please design the appropriate

Methods) and individual reliability data (i.e. reliability test report and estimated failure rate, etc).

reliability upon reviewing the Toshiba Semiconductor Reliability Handbook ("Handling Precautions"/Derating Concept and

Thermal Characteristics

| Characteristics | Symbol | Max | Unit |
|--|------------------------|-----|--------|
| Thermal resistance, channel to case | R _{th (ch-c)} | 1.0 | °C / W |
| Thermal resistance, channel to ambient | R _{th (ch−a)} | 50 | °C / W |

Note 1: Ensure that the channel temperature does not exceed 150°C.

Note 2: V_{DD} = 90 V, T_{ch} = 25°C (initial), L = 4.59 mH, R_G = 25 Ω , I_{AR} = 10 A

Note 3: Repetitive rating: pulse width limited by maximum channel temperature

This transistor is an electrostatic-sensitive device. Please handle with caution.

Unit: mm

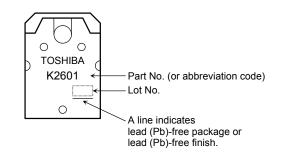
Electrical Characteristics (Ta = 25°C)

| Charao | cteristics | Symbol | Test Condition | Min | Тур. | Max | Unit |
|---|------------------|----------------------|---|-----|------|-----|------|
| Gate leakage cu | urrent | I _{GSS} | $V_{GS} = \pm 25 \text{ V}, V_{DS} = 0 \text{ V}$ | _ | _ | ±10 | μA |
| Gate-source br | eakdown voltage | V (BR) GSS | I _G = ±10 μA, V _{DS} = 0 V | ±30 | _ | _ | V |
| Drain cut-off cu | rrent | I _{DSS} | V _{DS} = 500 V, V _{GS} = 0 V | _ | _ | 100 | μA |
| Drain-source br | reakdown voltage | I (BR) DSS | I _D = 10 mA, V _{GS} = 0 V | 500 | _ | _ | V |
| Gate threshold | voltage | V _{th} | V _{DS} = 10 V, I _D = 1 mA | 2.0 | _ | 4.0 | V |
| Drain-source O | N resistance | R _{DS (ON)} | V _{GS} = 10 V, I _D = 5 A, | _ | 0.75 | 1.0 | Ω |
| Forward transfe | r admittance | Y _{fs} | V _{DS} = 10 V, I _D = 5 A | 3.5 | 7.0 | | S |
| Input capacitant | ce | C _{iss} | | _ | 1200 | _ | |
| Reverse transfer capacitance | | C _{rss} | V _{DS} = 10 V, V _{GS} = 0 V, f = 1 MHz | _ | 200 | | pF |
| Output capacita | nce | Coss | | _ | 550 | _ | |
| Switching time | Rise time | tr | $V_{GS} \stackrel{10 \text{ V}}{}_{0 \text{ V}} \int I_{D} = 5 \text{ A} \\ \downarrow O \\ \downarrow$ | _ | 30 | _ | - ns |
| | Turn-on time | t _{on} | | _ | 50 | _ | |
| | Fall time | tf | | _ | 45 | _ | |
| | Turn-off time | t _{off} | Duty $\leq 1\%$, t _w = 10 µs | _ | 180 | _ | |
| Total gate charge (gate-source plus gate-drain) | | Qg | | _ | 30 | _ | |
| Gate-source charge | | Q _{gs} | V _{DD} ≈ 400 V, V _{GS} = 10 V, I _D = 10 A | | 15 | — | nC |
| Gate-drain ("miller") Charge | | Q _{gd} | | | 15 | _ | |

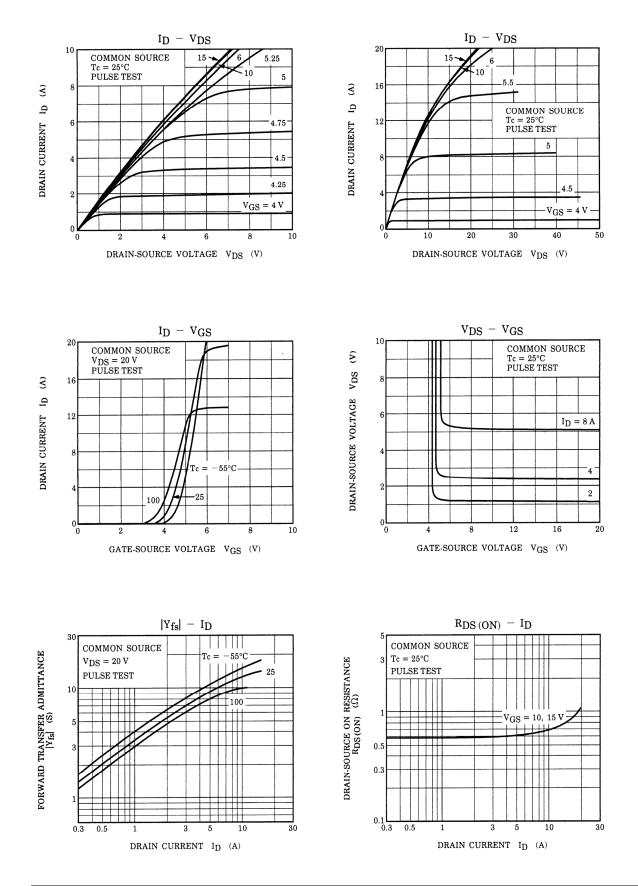
Source–Drain Ratings and Characteristics (Ta = 25°C)

| Characteristics | Symbol | Test Condition | Min | Тур. | Max | Unit |
|--|------------------|---|-----|------|------|------|
| Continuous drain reverse current (Note 1) | I _{DR} | — | _ | _ | 10 | А |
| Pulse drain reverse current (Note 1) | I _{DRP} | — | _ | _ | 40 | А |
| Forward voltage (diode) | VDSF | I _{DR} = 10 A, V _{GS} = 0 V | _ | _ | -1.7 | V |
| Reverse recovery time | t _{rr} | I _{DR} = 10 A, V _{GS} = 0 V | _ | 1200 | _ | ns |
| Reverse recovery charge | Qrr | dl _{DR} / dt = 100 A / µs | _ | 10 | _ | μC |

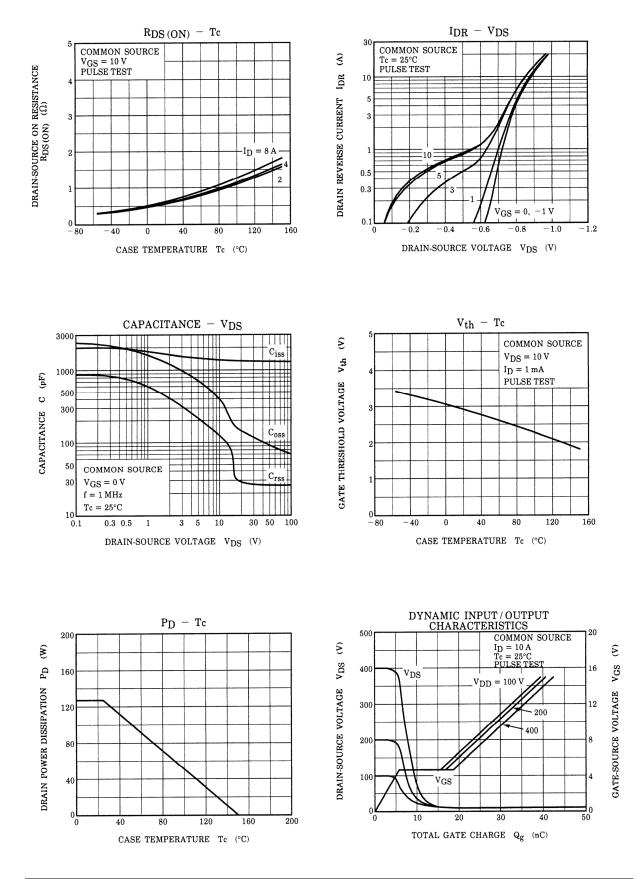
Marking

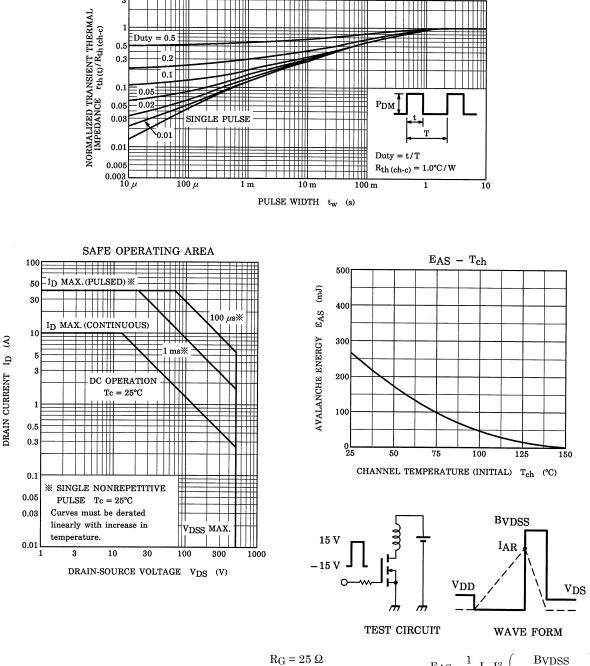


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 $r_{th} - t_w$

 $\begin{array}{l} R_{G} = 25 \ \Omega \\ V_{DD} = 90 \ V, \ L = 4.59 \ mH \end{array} \qquad \qquad \\ E_{AS} = \frac{1}{2} \cdot L \cdot I^{2} \cdot \left(\frac{B V_{DSS}}{B V_{DSS} - V_{DD}} \right) \end{array}$

RESTRICTIONS ON PRODUCT USE

20070701-EN

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